

Title: Semiconductor Package with Integrated Heat Spreader Attached to a Thermally Conductive Substrate Core
Inventor(s): Timothy M. Takeuchi
Atty. Docket No.: 42390P13557

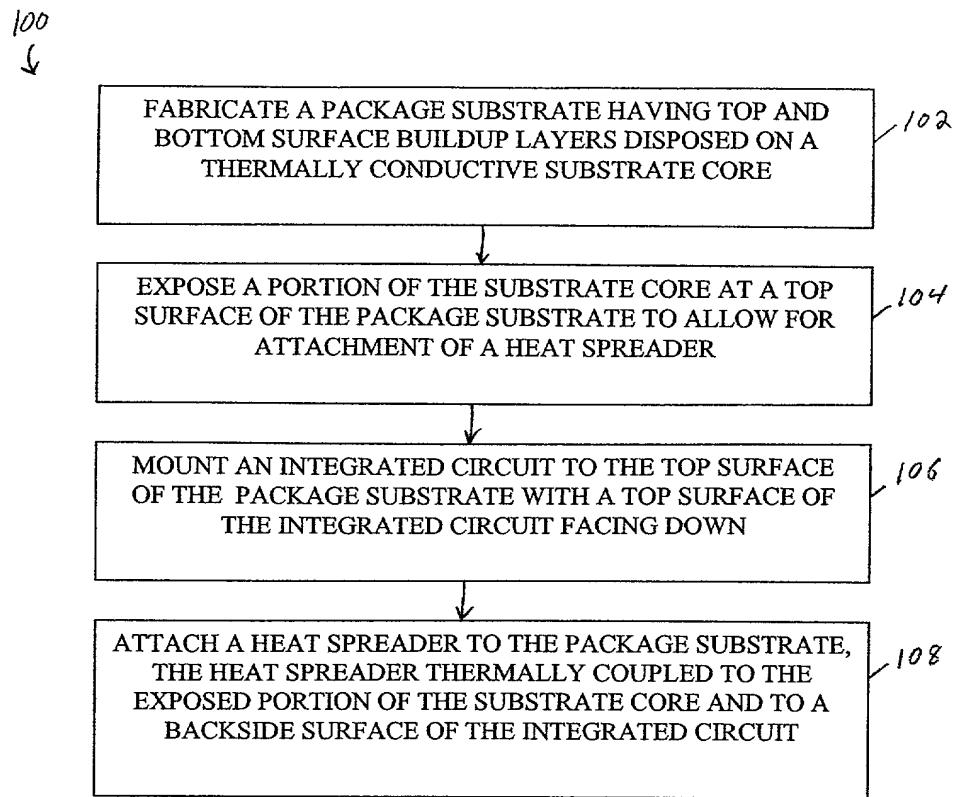
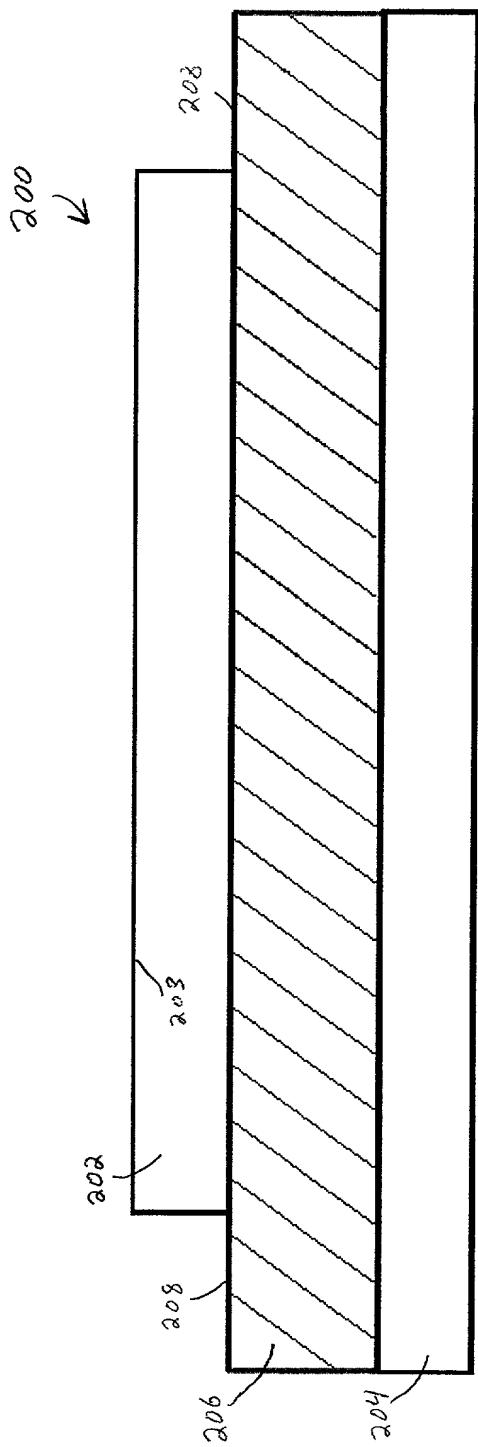


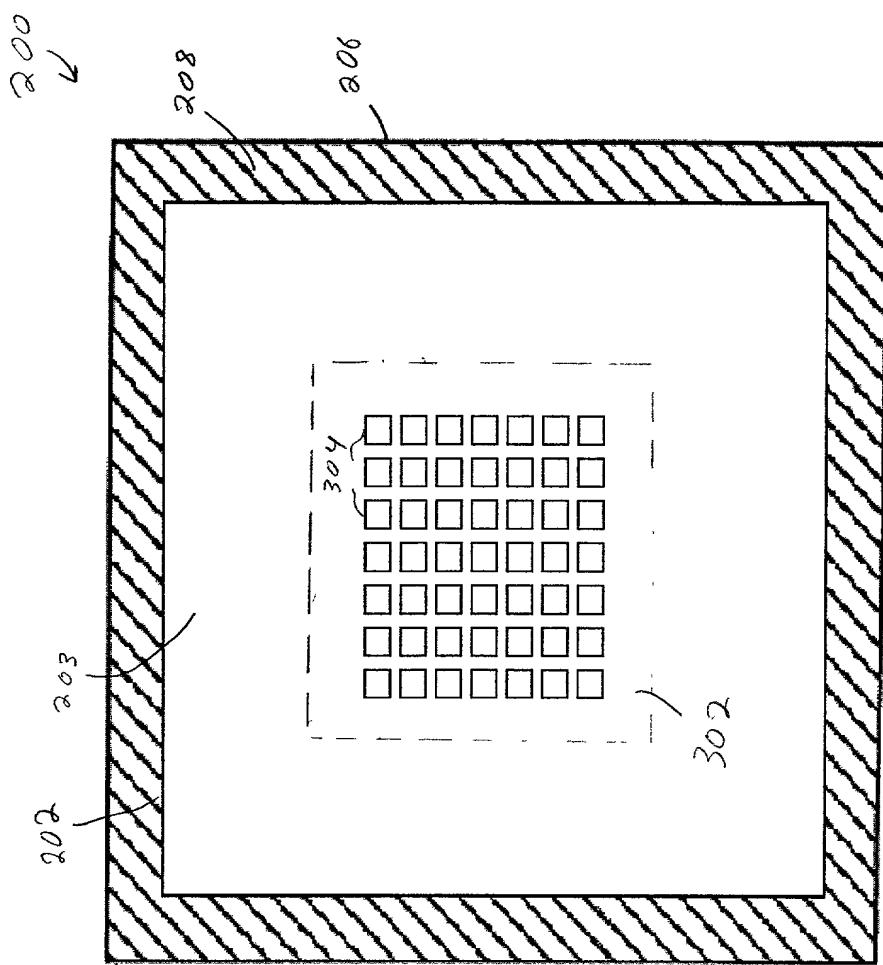
Figure 1

Figure 2



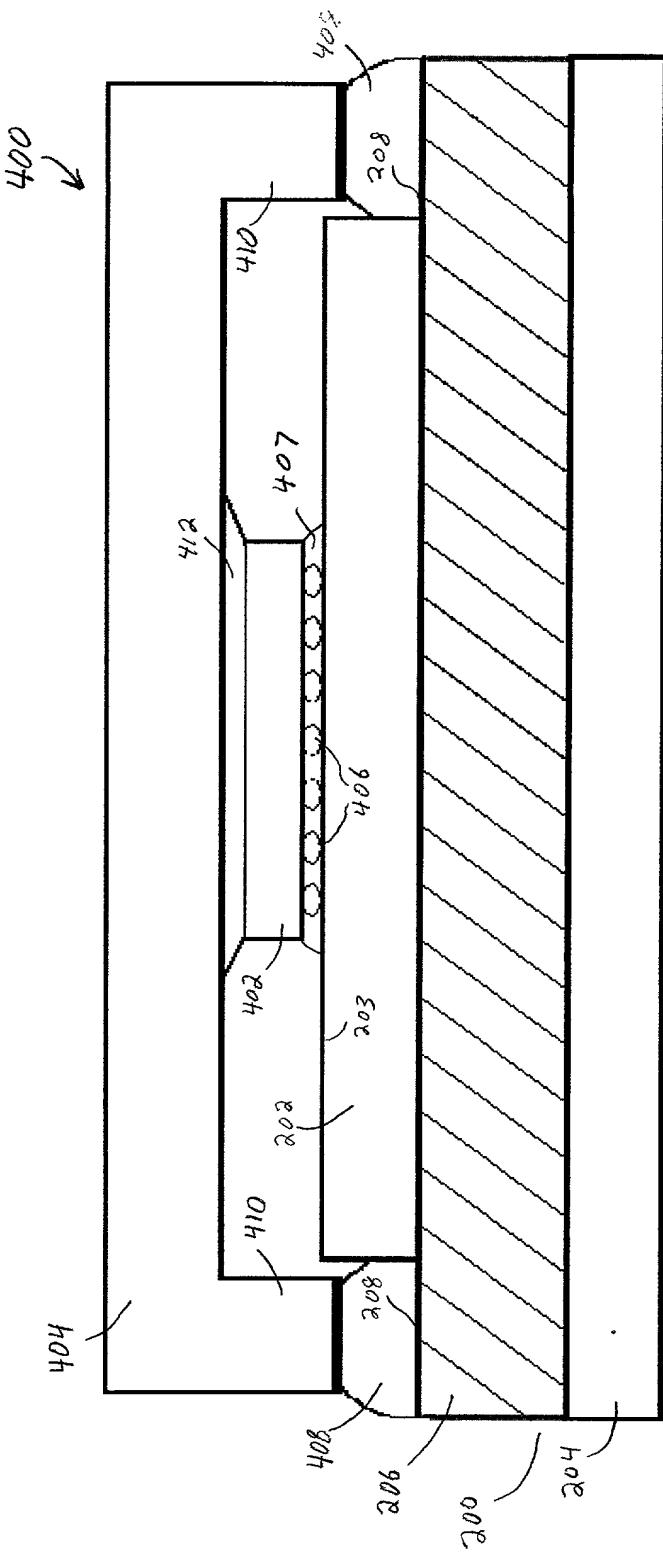
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Figure 3



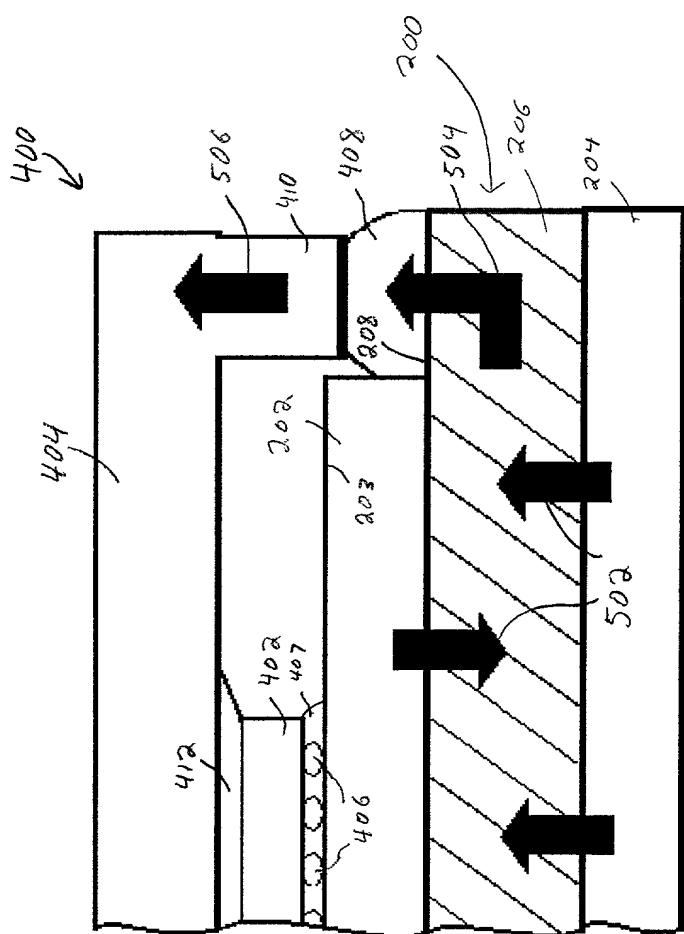
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Figure 4



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Figure 5



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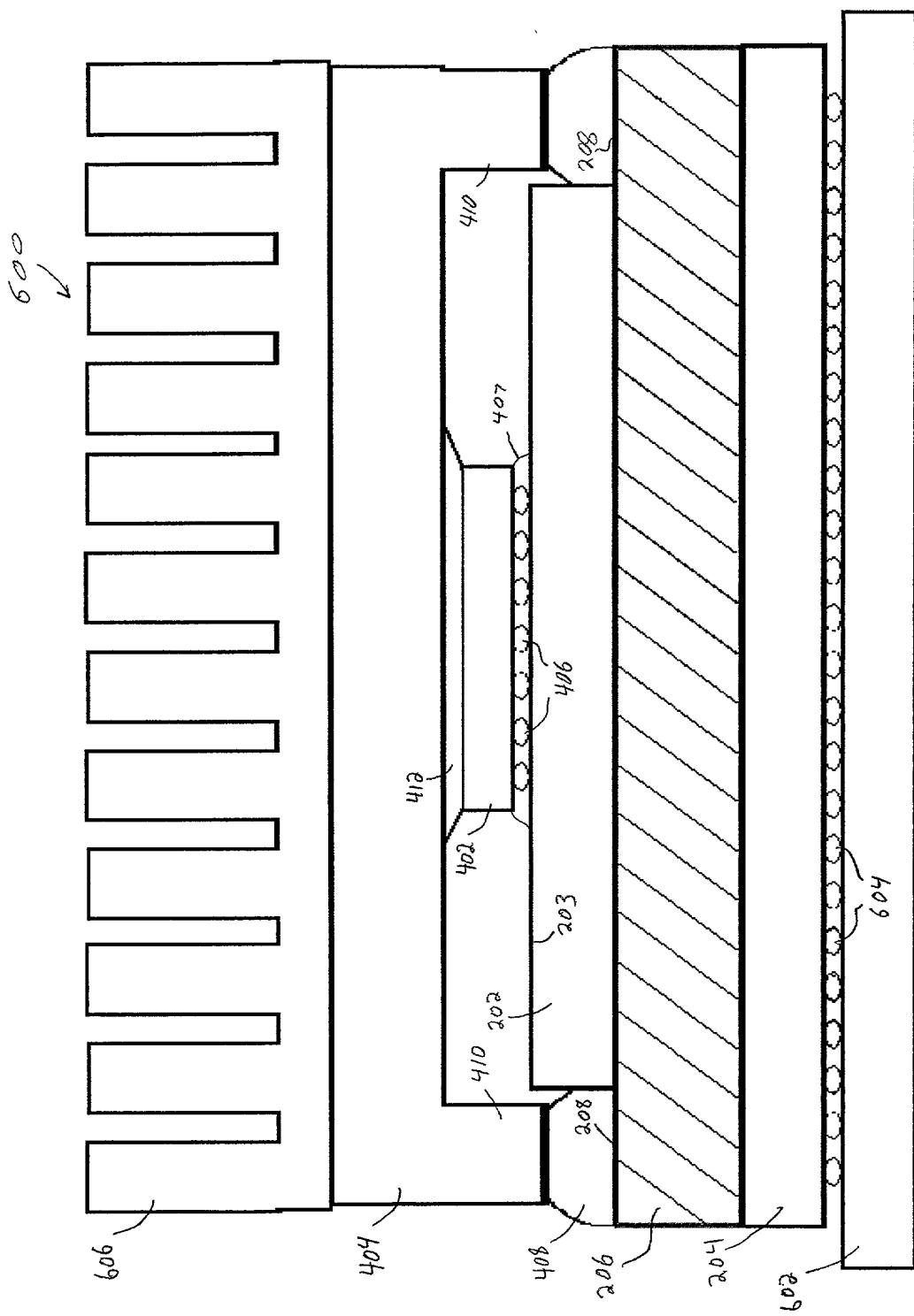
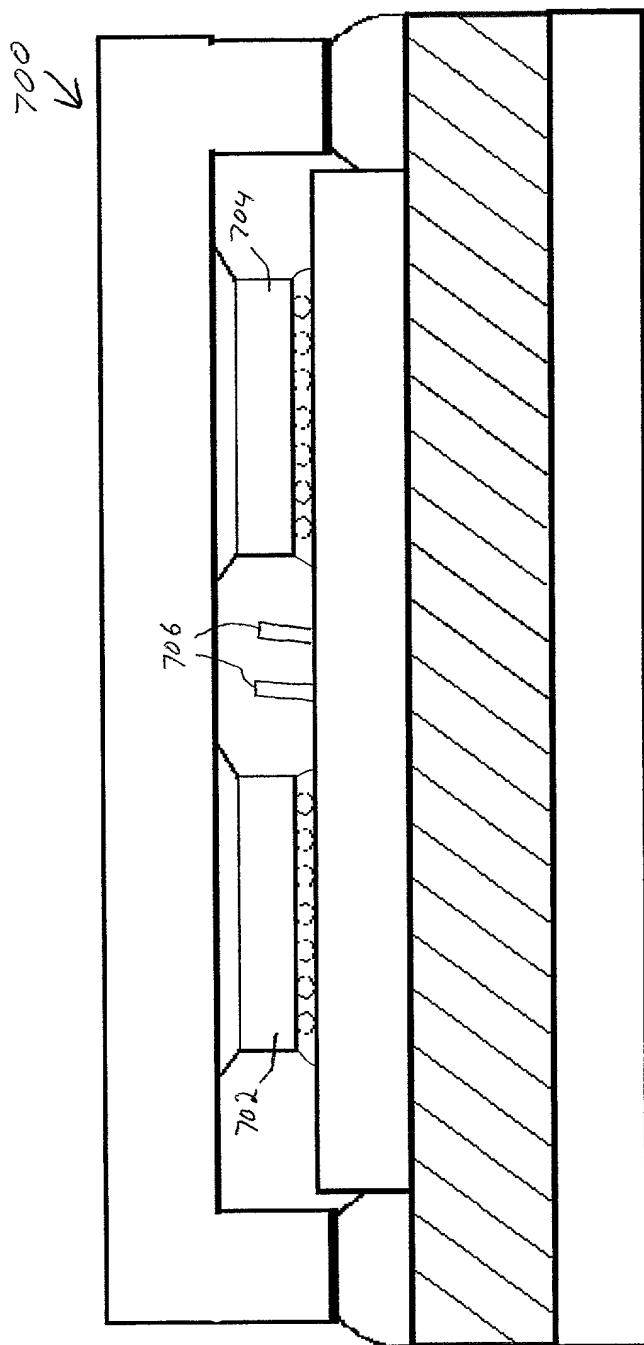


Figure 6

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Figure 7



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